

**SOT-23**

**SOT-323**

**Pin Definition:**

1. Gate
2. Source
3. Drain

**TSM2N7002K**
**60V N-Channel MOSFET**
**Features**

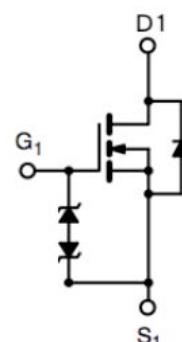
- Low On-Resistance
- ESD Protected 2kV
- High Speed Switching
- Low Voltage Drive

**Ordering Information**

<b>Part No.</b>	<b>Package</b>	<b>Packing</b>
TSM2N7002KCX RF	SOT-23	3Kpcs / 7" Reel
TSM2N7002KCU RF	SOT-323	3Kpcs / 7" Reel

**PRODUCT SUMMARY**

<b>V<sub>DS</sub> (V)</b>	<b>R<sub>D(on)</sub>(Ω)</b>	<b>I<sub>D</sub> (mA)</b>
60	2 @ V <sub>GS</sub> = 10V	300
	4 @ V <sub>GS</sub> = 4.5V	200

**Block Diagram**

**N-Channel MOSFET**
**Absolute Maximum Rating (Ta = 25°C unless otherwise noted)**

<b>Parameter</b>		<b>Symbol</b>	<b>Limit</b>	<b>Unit</b>
Drain-Source Voltage		V <sub>DS</sub>	60	V
Gate-Source Voltage		V <sub>GS</sub>	±20	V
Drain Current	Continuous @ T <sub>A</sub> =25°C	I <sub>D</sub>	300	mA
	Pulsed	I <sub>DM</sub>	800	
Drain Reverse Current	Continuous @ T <sub>A</sub> =25°C	I <sub>DR</sub>	300	mA
	Pulsed	I <sub>DMR</sub>	800	
Maximum Power Dissipation		P <sub>D</sub>	300	mW
Operating Junction Temperature		T <sub>J</sub>	+150	°C
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

**Thermal Performance**

<b>Parameter</b>		<b>Symbol</b>	<b>Limit</b>	<b>Unit</b>
Lead Temperature (1/8" from case)		T <sub>L</sub>	5	S
Junction to Ambient Thermal Resistance (PCB mounted)		R <sub>θJA</sub>	350	°C/W

**Notes:**

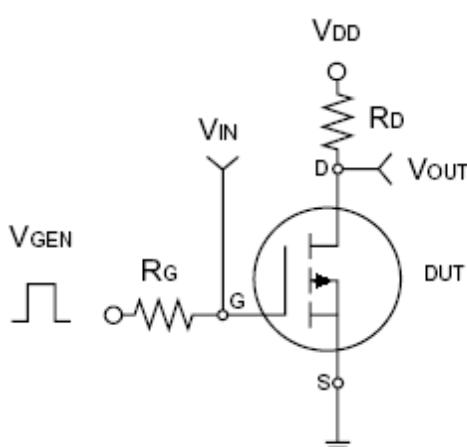
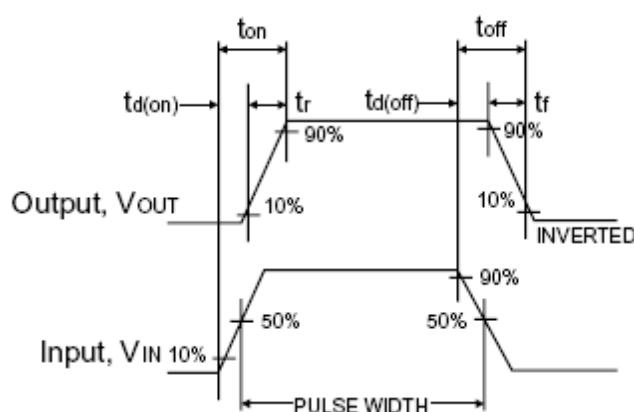
- a. Pulse width ≤300us, Duty cycle ≤2%
- b. When the device is mounted on a glass epoxy board with area measuring 1 x 0.75 x 0.62 inch.
- c. The power dissipation of the package may result in a continuous drain current.

**Electrical Specifications** ( $T_a = 25^\circ\text{C}$ , unless otherwise noted)

Parameter	Conditions	Symbol	Min	Typ	Max	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{GS} = 0\text{V}$ , $I_D = 250\mu\text{A}$	$BV_{DSS}$	60	--	--	V
Gate Threshold Voltage	$V_{DS} = V_{GS}$ , $I_D = 250\mu\text{A}$	$V_{GS(\text{TH})}$	1.0	1.5	2.5	V
Gate Body Leakage	$V_{GS} = \pm 20\text{V}$ , $V_{DS} = 0\text{V}$	$I_{GSS}$	--	--	$\pm 10$	$\mu\text{A}$
Zero Gate Voltage Drain Current	$V_{DS} = 60\text{V}$ , $V_{GS} = 0\text{V}$	$I_{DSS}$	--	--	1.0	$\mu\text{A}$
Drain-Source On-State Resistance	$V_{GS} = 10\text{V}$ , $I_D = 300\text{mA}$	$R_{DS(\text{ON})}$	--	1.2	2	$\Omega$
	$V_{GS} = 4.5\text{V}$ , $I_D = 100\text{mA}$		--	2	4	
Forward Transconductance	$V_{DS} = 10\text{V}$ , $I_D = 200\text{mA}$	$g_{fs}$	100	--	--	$\text{mS}$
Diode Forward Voltage	$I_S = 300\text{mA}$ , $V_{GS} = 0\text{V}$	$V_{SD}$	--	0.8	1.4	V
<b>Dynamic<sup>b</sup></b>						
Total Gate Charge	$V_{DS} = 10\text{V}$ , $I_D = 250\text{mA}$ , $V_{GS} = 4.5\text{V}$	$Q_g$	--	0.4	0.6	$\text{nC}$
Input Capacitance	$V_{DS} = 25\text{V}$ , $V_{GS} = 0\text{V}$ , $f = 1.0\text{MHz}$	$C_{iss}$	--	30	--	$\text{pF}$
Output Capacitance		$C_{oss}$	--	6	--	
Reverse Transfer Capacitance		$C_{rss}$	--	2.5	--	
<b>Switching<sup>c</sup></b>						
Turn-On Delay Time	$V_{DD} = 30\text{V}$ , $R_G = 10\Omega$	$t_{d(on)}$	--	--	25	$\text{nS}$
Turn-Off Delay Time	$I_D = 200\text{mA}$ , $V_{GEN} = 10\text{V}$	$t_{d(off)}$	--	--	35	

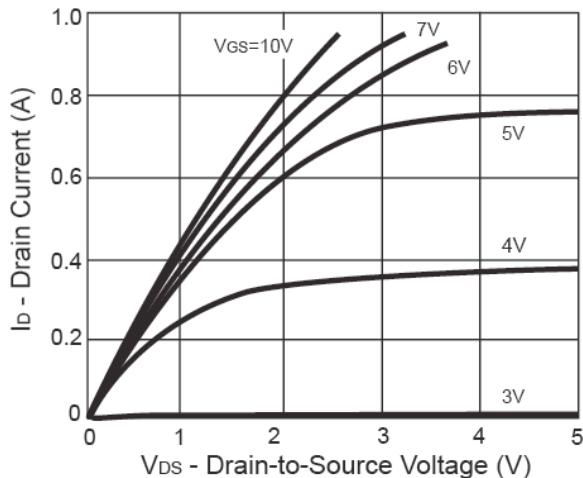
Notes:

- a. pulse test:  $PW \leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$
- b. For DESIGN AID ONLY, not subject to production testing.
- c. Switching time is essentially independent of operating temperature.

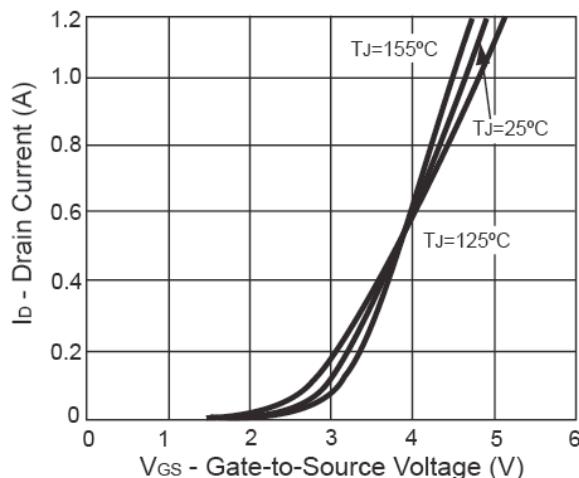

**Switching Test Circuit**

**Switching Waveforms**

### Electrical Characteristics Curve ( $T_a = 25^\circ\text{C}$ , unless otherwise noted)

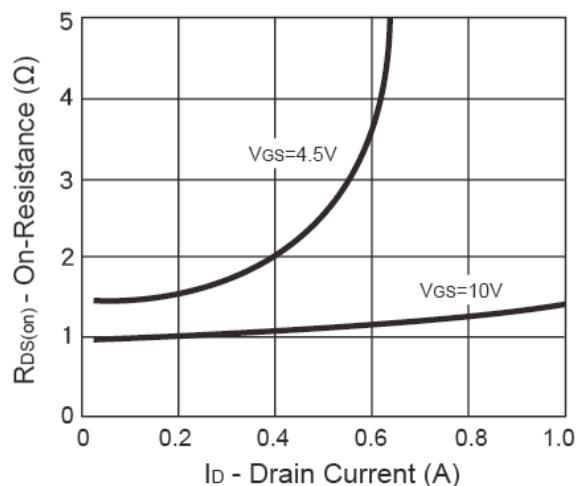
Output Characteristics



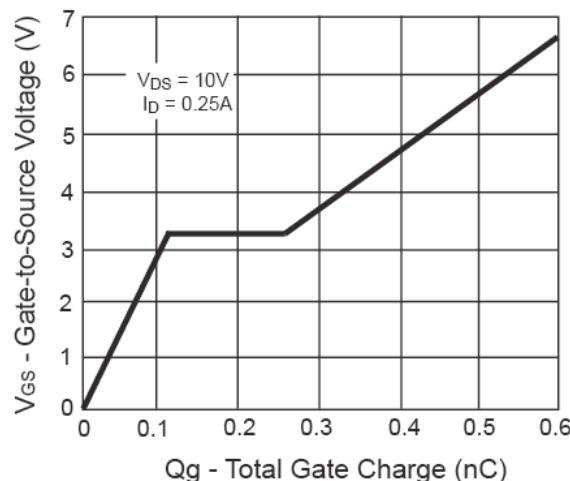
Transfer Characteristics



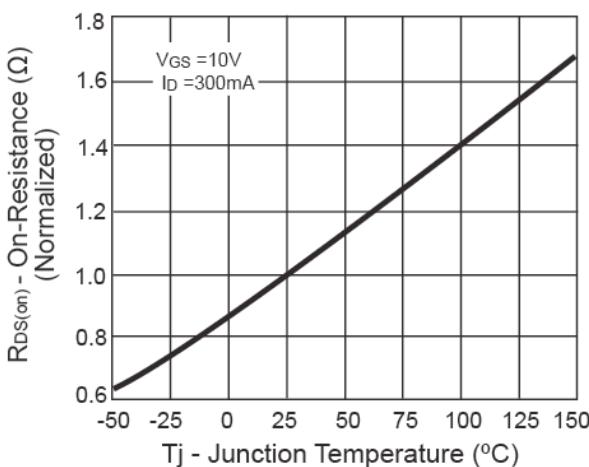
On-Resistance vs. Drain Current



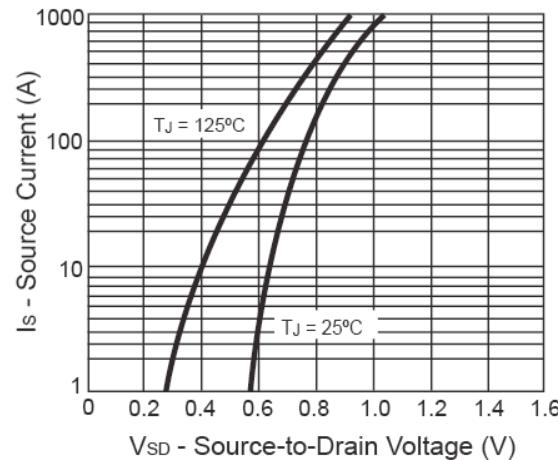
Gate Charge



On-Resistance vs. Junction Temperature

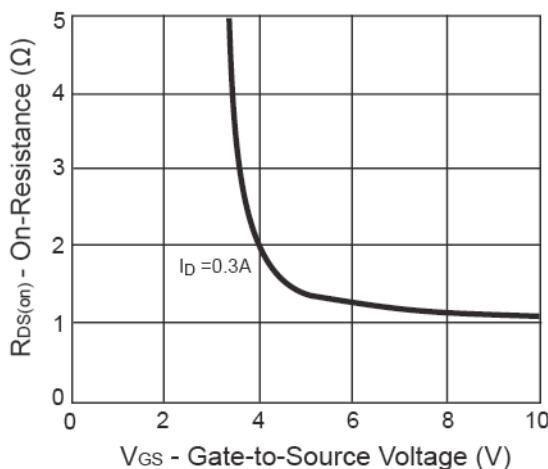


Source-Drain Diode Forward Voltage

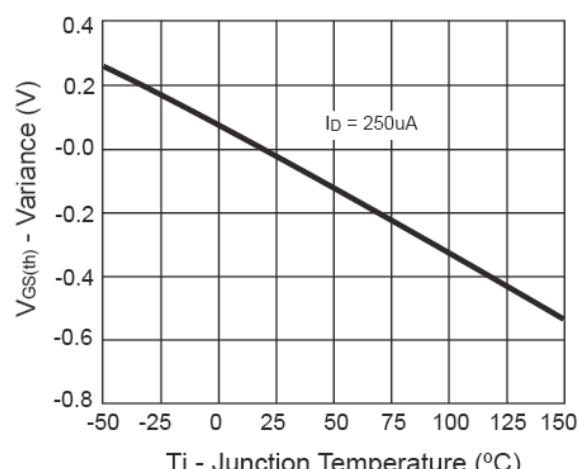


### Electrical Characteristics Curve ( $T_a = 25^\circ\text{C}$ , unless otherwise noted)

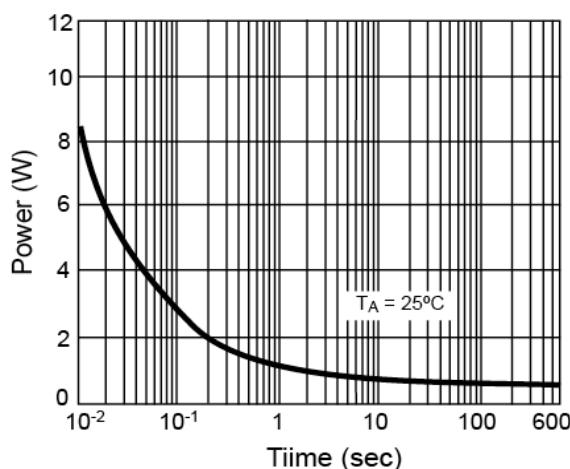
On-Resistance vs. Gate-Source Voltage



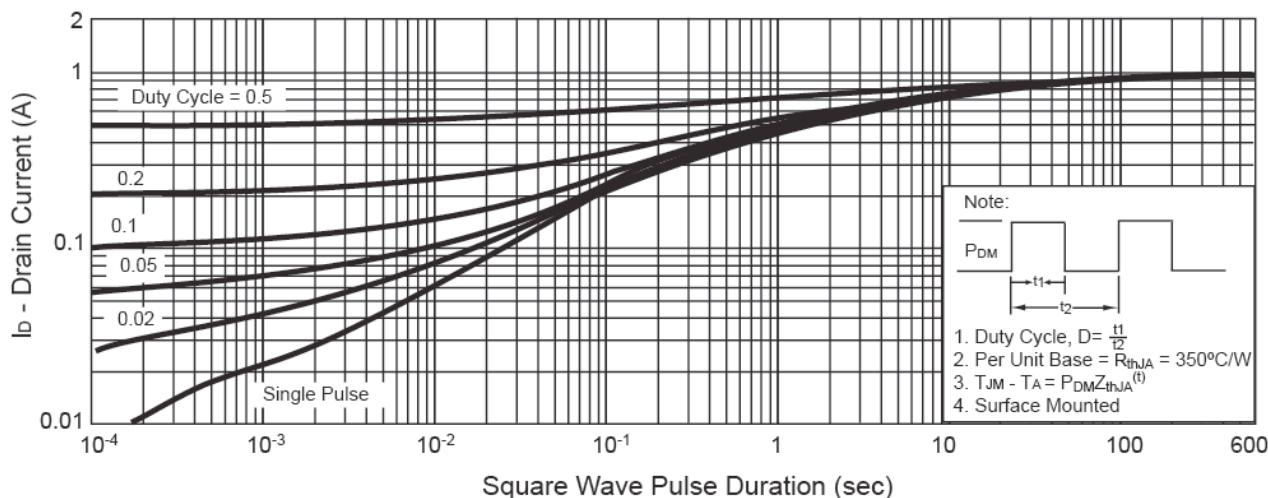
Threshold Voltage



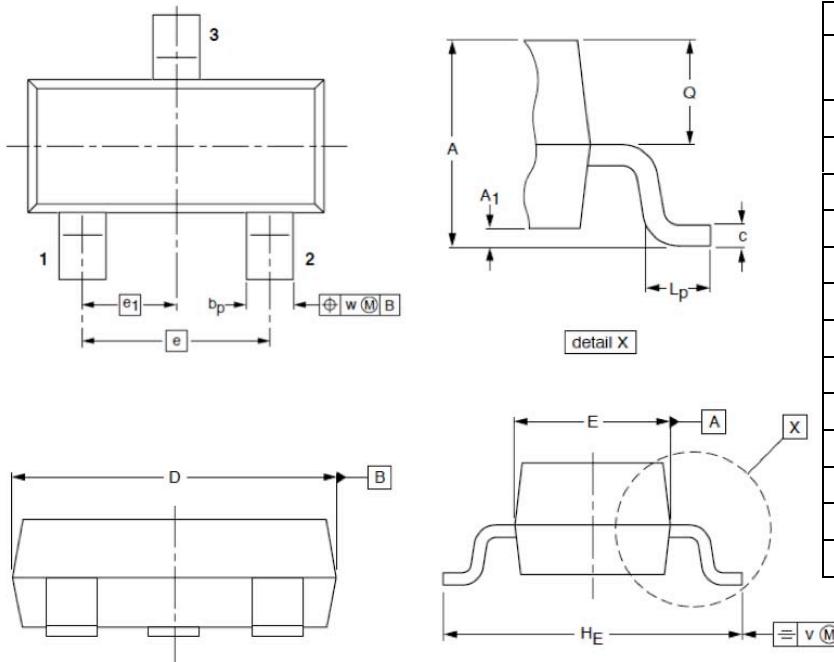
Single Pulse Power



Normalized Thermal Transient Impedance, Junction-to-Ambient

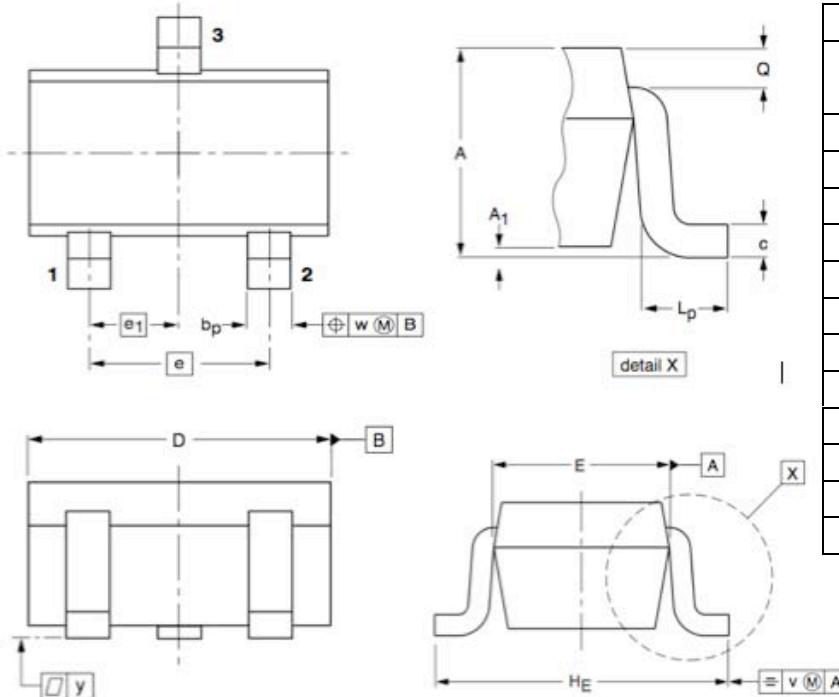


## SOT-23 Mechanical Drawing



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.00 BSC		0.039 BSC	
A1	--	0.10	--	0.004
b <sub>p</sub>	0.37	0.42	0.014	0.016
C	0.15	0.09	0.005	0.004
D	2.80	3.00	0.110	0.118
E	1.20	1.40	0.047	0.055
e	1.9 BSC		0.075 BSC	
e <sub>1</sub>	0.95 BSC		0.037 BSC	
H <sub>E</sub>	2.35	2.45	0.093	0.096
L <sub>p</sub>	0.15	0.45	0.005	0.018
Q	0.45	0.55	0.018	0.022
V	0.2 BSC		0.007 BSC	
W	0.1 BSC		0.004 BSC	

## SOT-323 Mechanical Drawing



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.80	1.10	0.031	0.043
A1	--	0.10	--	0.004
$b_p$	0.30	0.40	0.012	0.016
C	0.10	0.25	0.004	0.010
D	1.80	2.20	0.071	0.087
E	1.15	1.35	0.045	0.053
$e$	1.30 BSC		0.051 BSC	
$e_1$	0.65 BSC		0.026 BSC	
$H_E$	2.00	2.20	0.079	0.087
$L_p$	0.15	0.45	0.006	0.018
Q	0.20 BSC		0.007 BSC	
W	0.20 BSC		0.007 BSC	

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